AMENDMENTS TO THE TITLE

-- ~~FABRICATION~~ **COOLING APPARATUS FOR WAFER BAKING PLATE** --

AMENDMENTS TO THE SPECIFICATION

On page 2, please amend the paragraph beginning on line 10 as follows:

However, conventional ~~fabrication~~ cooling apparatuses for the wafer baking plate are slow in transferring heat and typically take a long time to achieve a uniform temperature distribution for the wafer baking plate. Even if the baking plate is cooled down rapidly, uniform temperature distribution takes a long time, thereby reducing wafer product yield.

On page 2, please amend the paragraph beginning on line 18 as follows:

It is, therefore, an object of the present invention to provide a ~~fabrication~~ cooling apparatus for a wafer baking plate, which shortens the time required to cool down the wafer baking plate and rapidly stabilizes temperature distribution.

On page 2, please amend the paragraph beginning on line 22 as follows:

The above object is achieved by a ~~fabrication~~ cooling apparatus for a wafer baking plate having a support plate for supporting a wafer, a heater under the support plate, and a heat transfer plate interposed between the support plate and the heater, for transferring heat. In the ~~fabrication~~ cooling apparatus, a hollow bore is formed in the heat transfer plate of the wafer baking plate and partially filled with a liquid working fluid. A cooling pipe is laid in the heat transfer plate, for circulating a cooling medium.

On page 4, please amend the paragraph beginning on line 13 as follows:

FIG. 1 is a perspective view of a wafer baking plate 100 according to a preferred embodiment of the present invention, FIG. 2 is a cross-sectional view of the wafer baking plate 100, taken along line A-A' illustrated in FIG. 1, FIG. 3 is a partial enlarged cross-sectional view of the wafer backing plate 100, and FIG. 4 is a cross-sectional view of the wafer baking plate 100, taken along line B-B' illustrated in FIG. 2. As illustrated in FIGs. 1 to 4, the wafer baking plate 100 is comprised of a support plate 101, a heater 102 under the support plate 101, and a heat transfer plate 103 between the support plate

101 and the heater 102. The wafer baking plate 100 includes a ~~fabrication~~ cooling apparatus having a cooling pipe 105 laid inside the heat transfer plate 103.

On page 7, please amend the paragraph beginning on line 7 as follows:

Referring to FIG. 12, it is noted from curves ① and ② that the average temperature of the baking plate 100 drops to 100°C 15 seconds after the ~~fabrication~~ cooling apparatus starts to operate in the present invention. Then the cooling water injection is discontinued and the cooling pipe is filled with air. Thirty seconds later, the temperature deviation of the baking plate 100 is reduced markedly, and 50 seconds later, its temperature distribution is stabilized.

On page 7, please amend the paragraph beginning on line 14 as follows:

FIG. 13 shows a graph 209 illustrating temperature change in a wafer baking plate according to conventional natural cooling method. While the natural cooling leads to a relatively uniform temperature distribution on the wafer baking plate during cooling, 45 minutes is taken to cool the wafer baking plate from 150°C to 100°C, thereby significantly decreasing product yield, as illustrated in FIG. 13. On the contrary, the ~~fabrication~~ cooling apparatus of the present invention rapidly cools the baking plate, achieving a uniform temperature distribution only in 50 seconds.

On page 7, please amend the paragraph beginning on line 23 as follows:

In accordance with the present invention as described above, the ~~fabrication~~ cooling apparatus for a wafer baking plate has a cooling pipe laid in a heat transfer plate partially filled with a liquid working fluid, for rapid cooling of the wafer baking plate. Since the heating and cooling of the baking plate is carried out via the working fluid, the temperature is uniform across the baking plate.